L Number	Hits	Search Text	DB	Time stamp
1	0	substrate same roughness near3 back near2 surface same radius	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 11:00
2	1	substrate same roughness near3 back near2 surface same diameter	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 11:02
3	7	wafer same back near2 surface same (varied or varying or varies or change) with roughness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 11:04
-	26	wafer same roughness same backside near2 surface	USPAT	2003/09/30 12:57
-	1		USPAT	2003/09/30 12:56
-	0		USPAT	2003/09/30 12:56
-	0		USPAT	2003/09/30 12:56
-	0		USPAT	2003/09/30 12:56
-	0		USPAT	2003/09/30 12:56
-	1		USPAT	2003/09/30 12:56
-	0		USPAT	2003/09/30 12:56
-	0		USPAT	2003/09/30 12:56
-	0		USPAT	2003/09/30 12:56
-	9	wafer same roughness same backside near2 surface	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 10:59
-	32	wafer same roughness near3 backside near2 surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 14:57
-	1	wafer same roughness near3 backside near2 surface same radius	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 14:57
-	1	wafer same roughness near3 back near2 surface same radius	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 11:00
-	3	wafer same back near2 surface same (varied or various or change)near3 roughness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 15:17